



## STL21N65M5

N-channel 650 V, 0.150  $\Omega$ , 17 A PowerFLAT™ (8x8) HV  
ultra low gate charge MDmesh™ V power MOSFET

### Features

Type	V <sub>DSS</sub> @ T <sub>Jmax</sub>	R <sub>DS(on)</sub> max	I <sub>D</sub>
STL21N65M5	710 V	< 0.179 $\Omega$	17 A <sup>(1)</sup>

1. The value is rated according to R<sub>thj-case</sub>

- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

### Application

Switching applications

### Description

The device is N-channel MDmesh™ V Power MOSFET based on an innovative proprietary vertical process technology, which is combined with STMicroelectronics' well-known PowerMESH™ horizontal layout structure. The resulting product has extremely low on-resistance, which is unmatched among silicon-based Power MOSFETs, making it especially suitable for applications which require superior power density and outstanding efficiency.

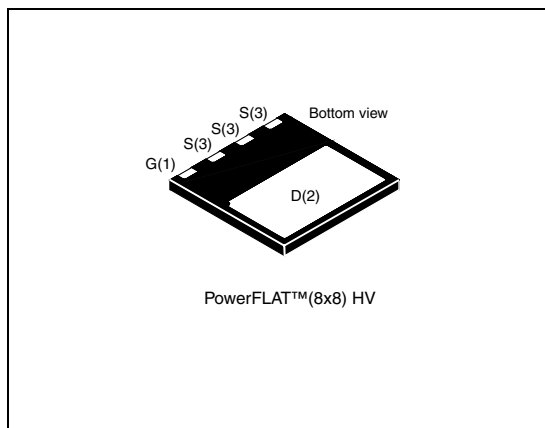


Figure 1. Internal schematic diagram

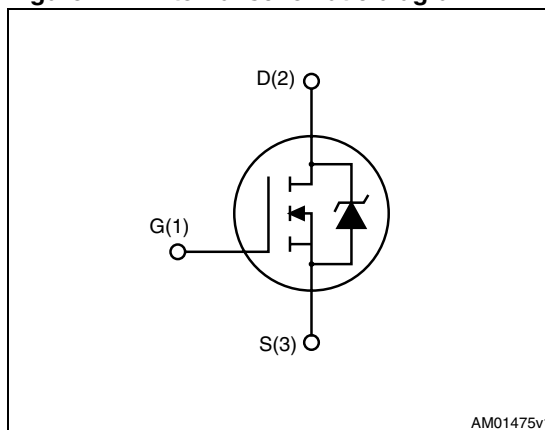


Table 1. Device summary

Order code	Marking	Package	Packaging
STL21N65M5	21N65M5	PowerFLAT™ (8x8) HV	Tape and reel

## Contents

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage ( $V_{GS} = 0$ )	650	V
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	17	A
$I_D^{(1)}$	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	11	A
$I_{DM}^{(1),(2)}$	Drain current (pulsed)	68	A
$I_D^{(3)}$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	2.7	A
$I_D^{(3)}$	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	1.7	A
$I_{DM}^{(2),(3)}$	Drain current (pulsed)	10.8	A
$P_{TOT}^{(3)}$	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$ (steady state)	3	W
$P_{TOT}^{(1)}$	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$ (steady state)	125	W
$I_{AR}$	Avalanche current, repetitive or not-repetitive (pulse width limited by $T_j$ max)	5	A
$E_{AS}$	Single pulse avalanche energy (starting $T_j = 25\text{ }^\circ\text{C}$ , $I_D = I_{AR}$ , $V_{DD} = 50\text{ V}$ )	400	mJ
$dv/dt^{(4)}$	Peak diode recovery voltage slope	15	V/ns
$T_{stg}$	Storage temperature	- 55 to 150	$^\circ\text{C}$
$T_j$	Max. operating junction temperature	150	$^\circ\text{C}$

1. The value is rated according to  $R_{thj-case}$ .
2. Pulse width limited by safe operating area.
3. When mounted on FR-4 board of  $1\text{ inch}^2$ , 2oz Cu.
4.  $I_{SD} \leq 17\text{ A}$ ,  $di/dt \leq 400\text{ A}/\mu\text{s}$ ,  $V_{Peak} < V_{(BR)DSS}$ ,  $V_{DD} = 400\text{ V}$ .

**Table 3. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	1	$^\circ\text{C}/\text{W}$
$R_{thj-amb}^{(1)}$	Thermal resistance junction-amb max	45	$^\circ\text{C}/\text{W}$

1. When mounted on  $1\text{ inch}^2$  FR-4 board, 2 oz Cu

## 2 Electrical characteristics

( $T_C = 25\text{ °C}$  unless otherwise specified)

**Table 4. On /off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}$ , $V_{GS} = 0$	650			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating}$ , $T_C = 125\text{ °C}$			1 100	$\mu\text{A}$ $\mu\text{A}$
$I_{GSS}$	Gate-body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 25\text{ V}$			100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	3	4	5	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$ , $I_D = 8.5\text{ A}$		0.150	0.179	$\Omega$

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0$	-	1950	-	pF
$C_{oss}$	Output capacitance			46		pF
$C_{rss}$	Reverse transfer capacitance			3		pF
$C_{o(tr)}^{(1)}$	Equivalent capacitance time related	$V_{DS} = 0\text{ to }520\text{ V}$ , $V_{GS} = 0$	-	133	-	pF
$C_{o(er)}^{(2)}$	Equivalent capacitance energy related			44		pF
$R_G$	Intrinsic gate resistance	$f = 1\text{ MHz}$ open drain	-	2.5	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 520\text{ V}$ , $I_D = 8.5\text{ A}$ , $V_{GS} = 10\text{ V}$ (see <a href="#">Figure 16</a> )	-	50	-	nC
$Q_{gs}$	Gate-source charge			13		nC
$Q_{gd}$	Gate-drain charge			23		nC

- $C_{oss\text{ eq}}$  time related is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$
- $C_{oss\text{ eq}}$  energy related is defined as a constant equivalent capacitance giving the same stored energy as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(off)}$	Turn-off delay time	$V_{DD} = 400\text{ V}$ , $I_D = 11\text{ A}$ ,		37		ns
$t_r$	Rise time	$R_G = 4.7\ \Omega$ , $V_{GS} = 10\text{ V}$	-	10	-	ns
$t_c$	Cross time	(see <a href="#">Figure 17</a> ),		24		ns
$t_f$	Fall time	(see <a href="#">Figure 20</a> )		12		ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		17	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		68	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 17\text{ A}$ , $V_{GS} = 0$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 17\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$	-	294		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 100\text{ V}$ (see <a href="#">Figure 17</a> )	-	4		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current			28		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 17\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$	-	340		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 100\text{ V}$ , $T_j = 150\text{ }^\circ\text{C}$	-	5		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see <a href="#">Figure 17</a> )		29		A

1. Pulse width limited by safe operating area

2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

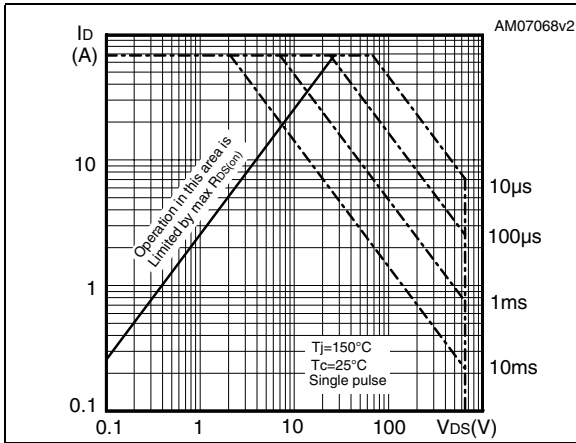


Figure 3. Thermal impedance

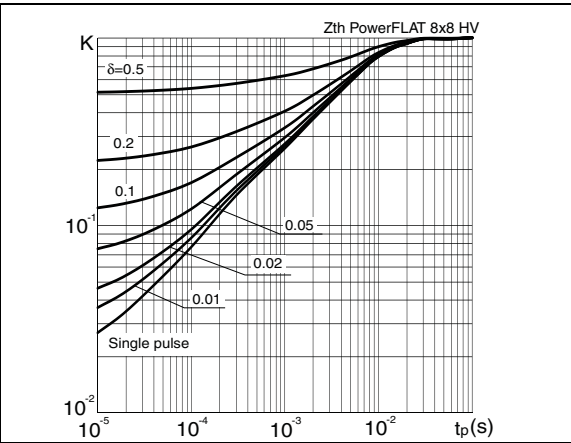


Figure 4. Output characteristics

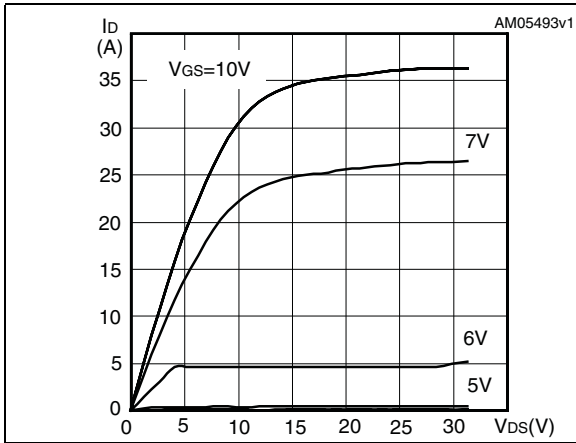


Figure 5. Transfer characteristics

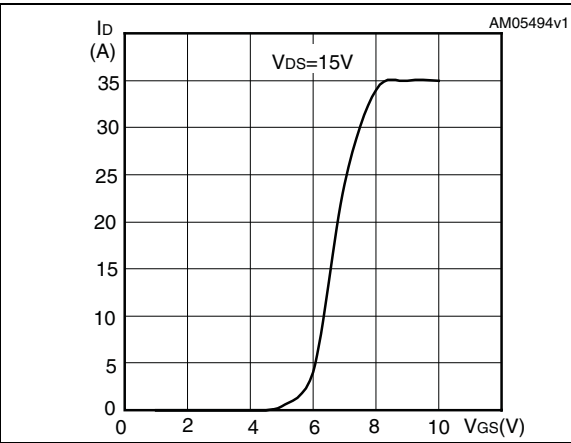


Figure 6. Gate charge vs gate-source voltage

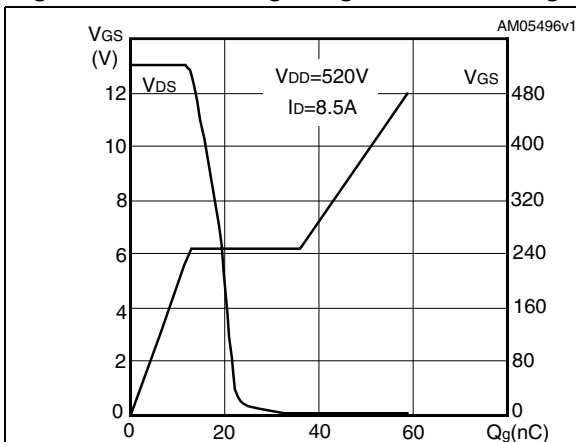


Figure 7. Static drain-source on resistance

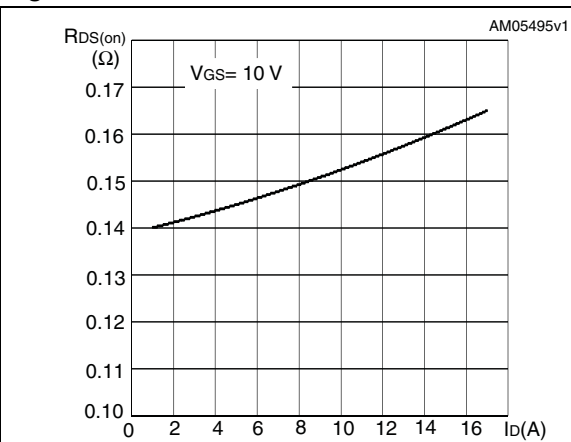


Figure 8. Output capacitance stored energy      Figure 9. Capacitance variations

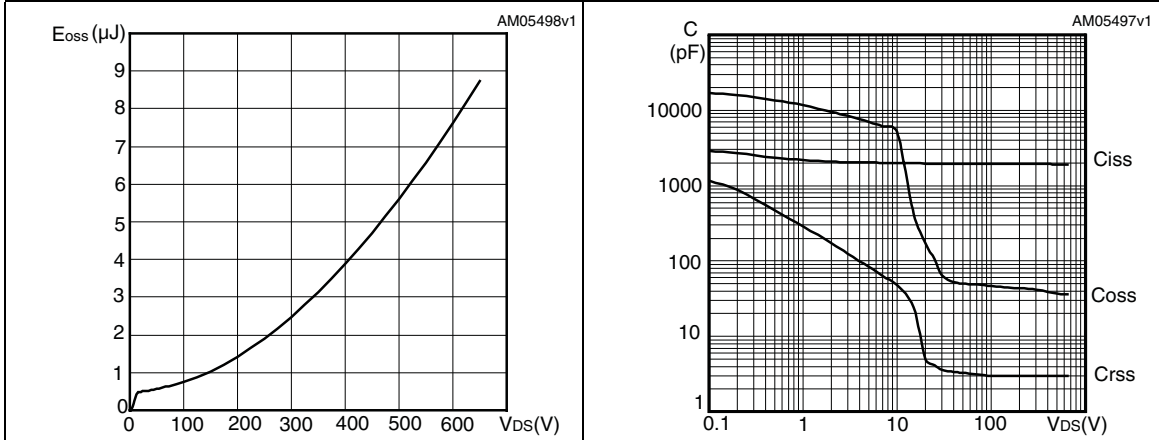


Figure 10. Normalized gate threshold voltage vs temperature      Figure 11. Normalized on resistance vs temperature

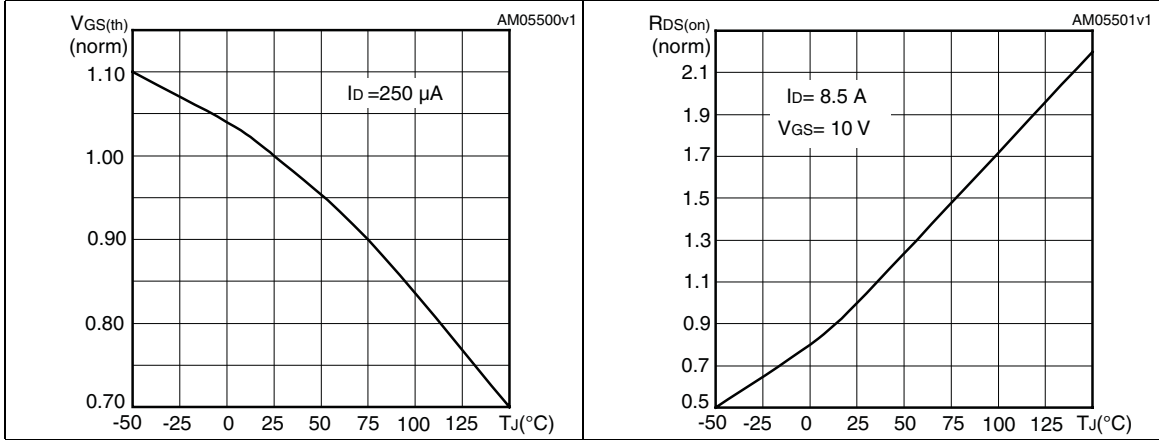


Figure 12. Source-drain diode forward characteristics      Figure 13. Normalized  $B_{VDSS}$  vs temperature

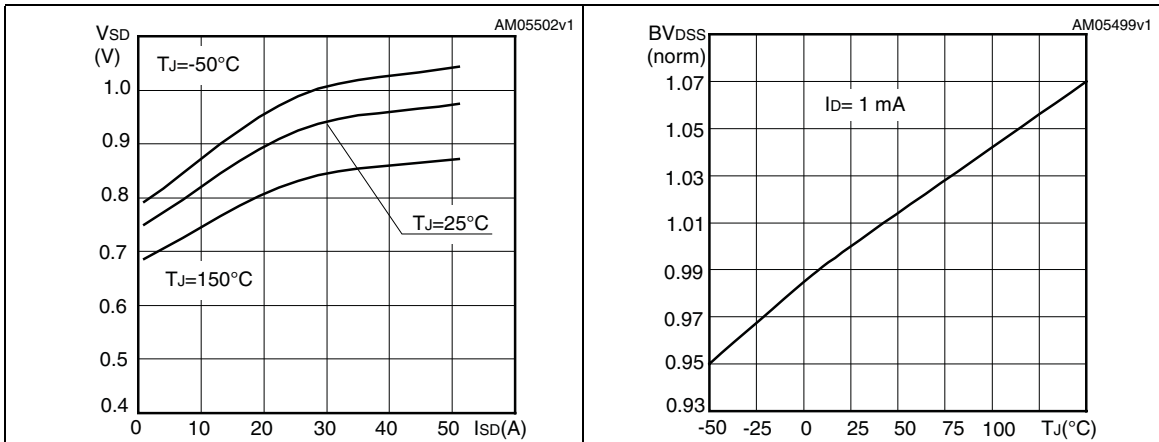
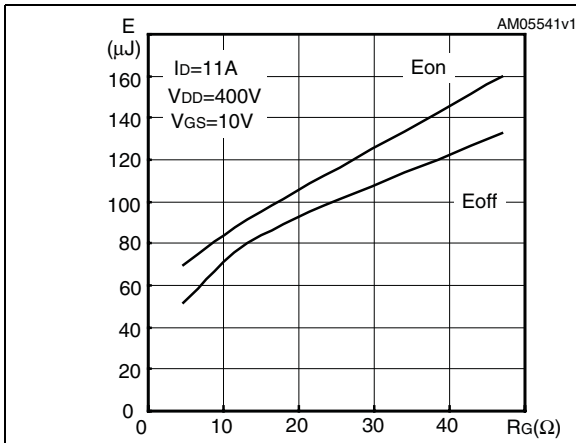


Figure 14. Switching losses vs gate resistance  
(1)



1.  $E_{on}$  including reverse recovery of a SiC diode



### 3 Test circuits

Figure 15. Switching times test circuit for resistive load

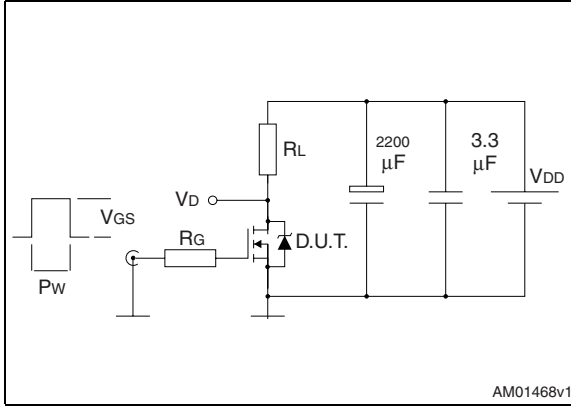


Figure 16. Gate charge test circuit

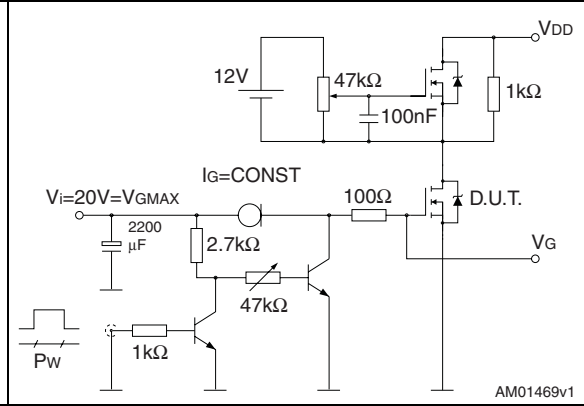


Figure 17. Test circuit for inductive load switching and diode recovery times

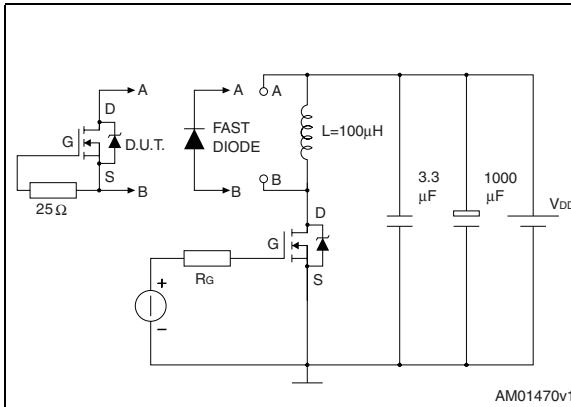


Figure 18. Unclamped inductive load test circuit

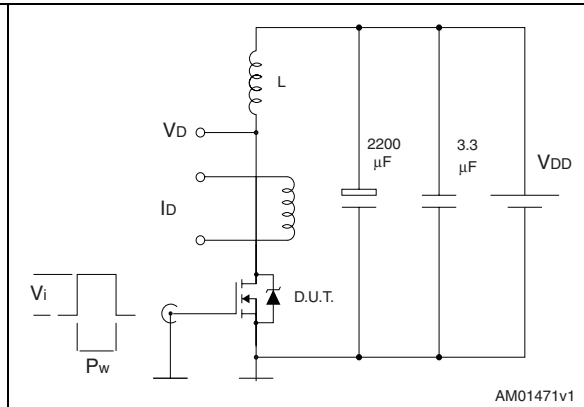


Figure 19. Unclamped inductive waveform

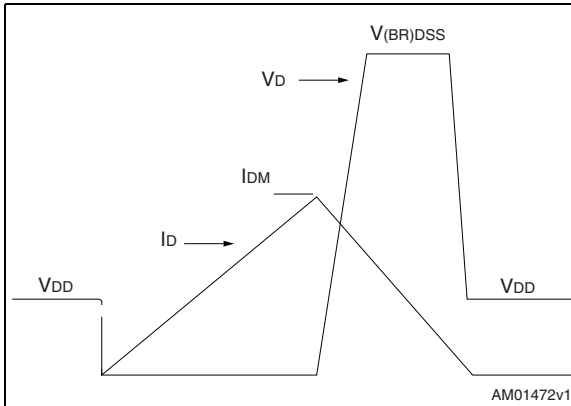
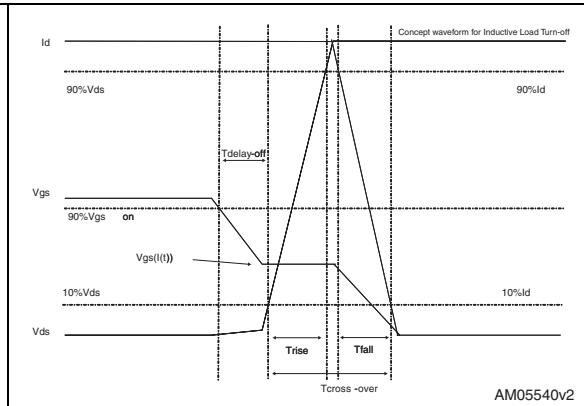


Figure 20. Switching time waveform



## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

Table 8. PowerFLAT™ 8x8 HV mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.80	0.90	1.00
A1		0.02	0.05
b	0.95	1.00	1.05
c		0.10	
D		8.00	
E		8.00	
D2	7.05	7.20	7.30
E2	4.15	4.30	4.40
e		2.00	
L	0.40	0.50	0.60

Figure 21. PowerFLAT™ 8x8 HV drawing mechanical data

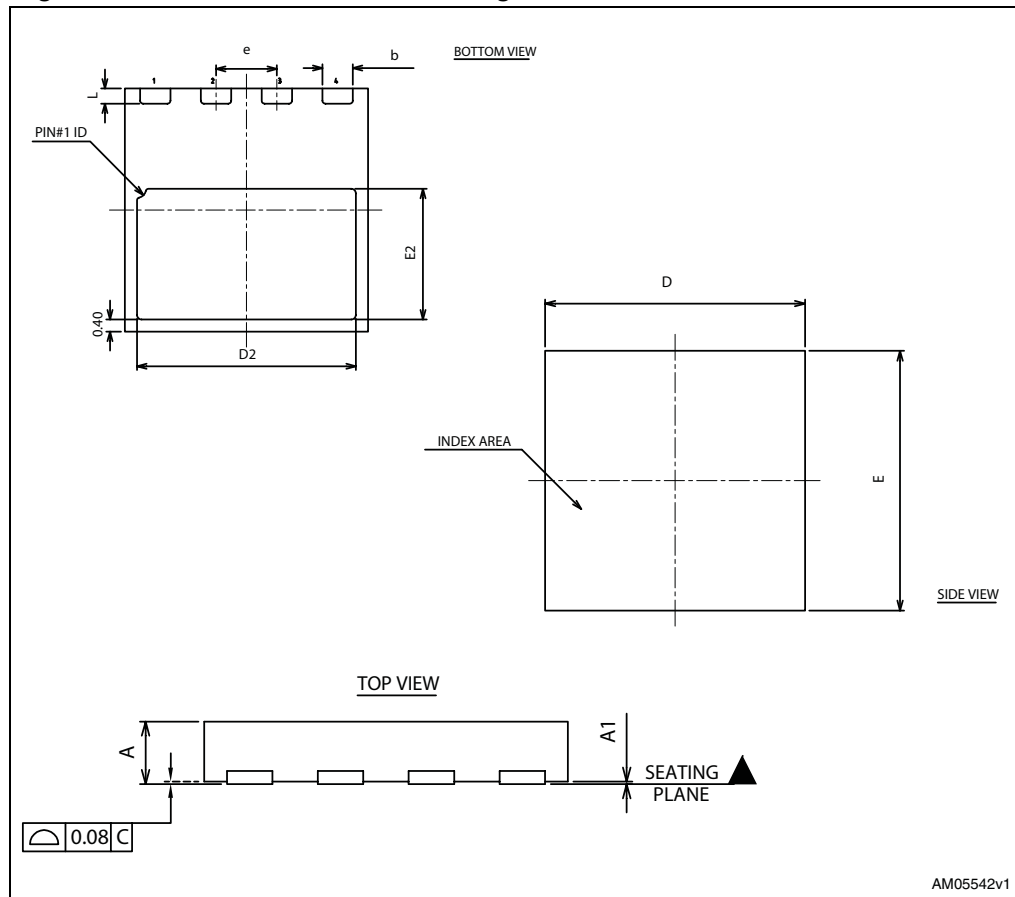
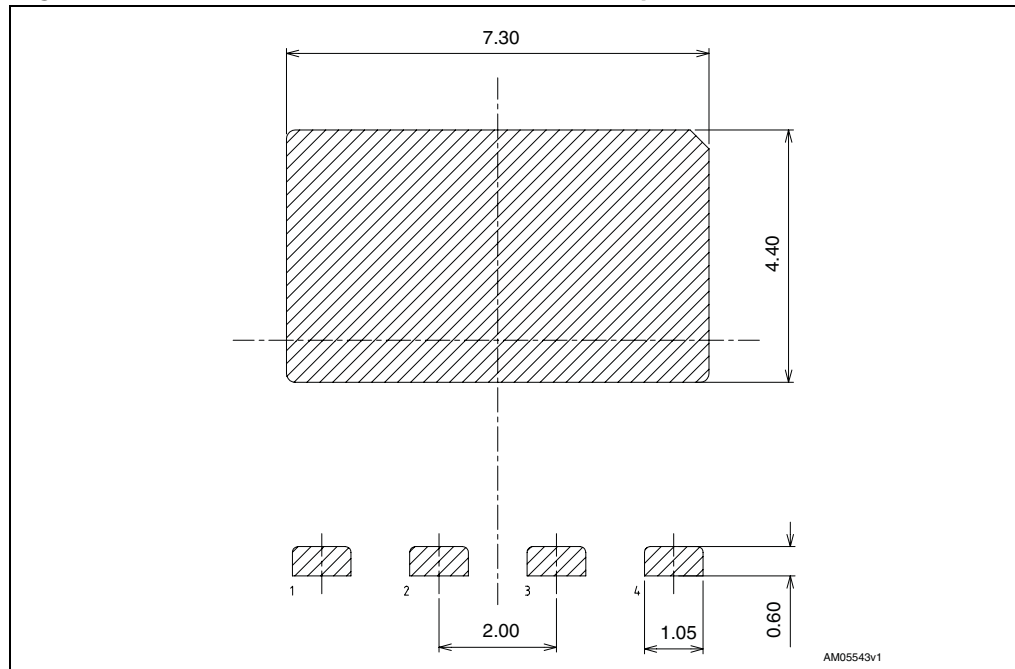


Figure 22. PowerFLAT™ 8x8 HV recommended footprint



## 5 Revision history

**Table 9. Document revision history**

Date	Revision	Changes
28-Apr-2010	1	First release.
14-Jun-2010	2	$R_{DS(on)}$ typical value has been corrected.
07-Apr-2011	3	<i>Figure 2: Safe operating area</i> , <i>Figure 3: Thermal impedance</i> and <i>Figure 7: Static drain-source on resistance</i> have been updated.

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